



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2826
\$

10/10
7/5/2003
4-13-23

In re application of

U-MING KO

Serial No. 09/723,563 (TI-29632)

Filed November 28, 2000

For: INPUT/OUTPUT ARCHITECTURE FOR INTEGRATED CIRCUITS

Art Unit 2826

Examiner Alexander O. Williams

Commissioner for Patents
Washington, D. C. 20231

Sir:

RECEIVED
APR 11 2003
TECHNOLOGY CENTER 2800

AMENDMENT UNDER 37 C.F.R. 1.111

In response to the Office action dated November 6, 2002, please amend the
above-identified application as follows:

In the claims:

Cancel claims 11 to 41 in favor of the following claims:

-
42. An integrated circuit having a plurality of I/O modules, comprising:
- a substrate;
 - a bond pad disposed on said substrate;
 - an electrostatic discharge device disposed in the substrate, the electrostatic
discharge device being at least partially disposed beneath the bond pad;
 - an I/O buffer formed in the substrate and connected to the bond pad, the I/O
buffer providing communication between the bond pad and circuitry disposed in the

Cont.

4/15/2003 DSASFAT 00400007 200646
1 FC:1201 336.00 CH